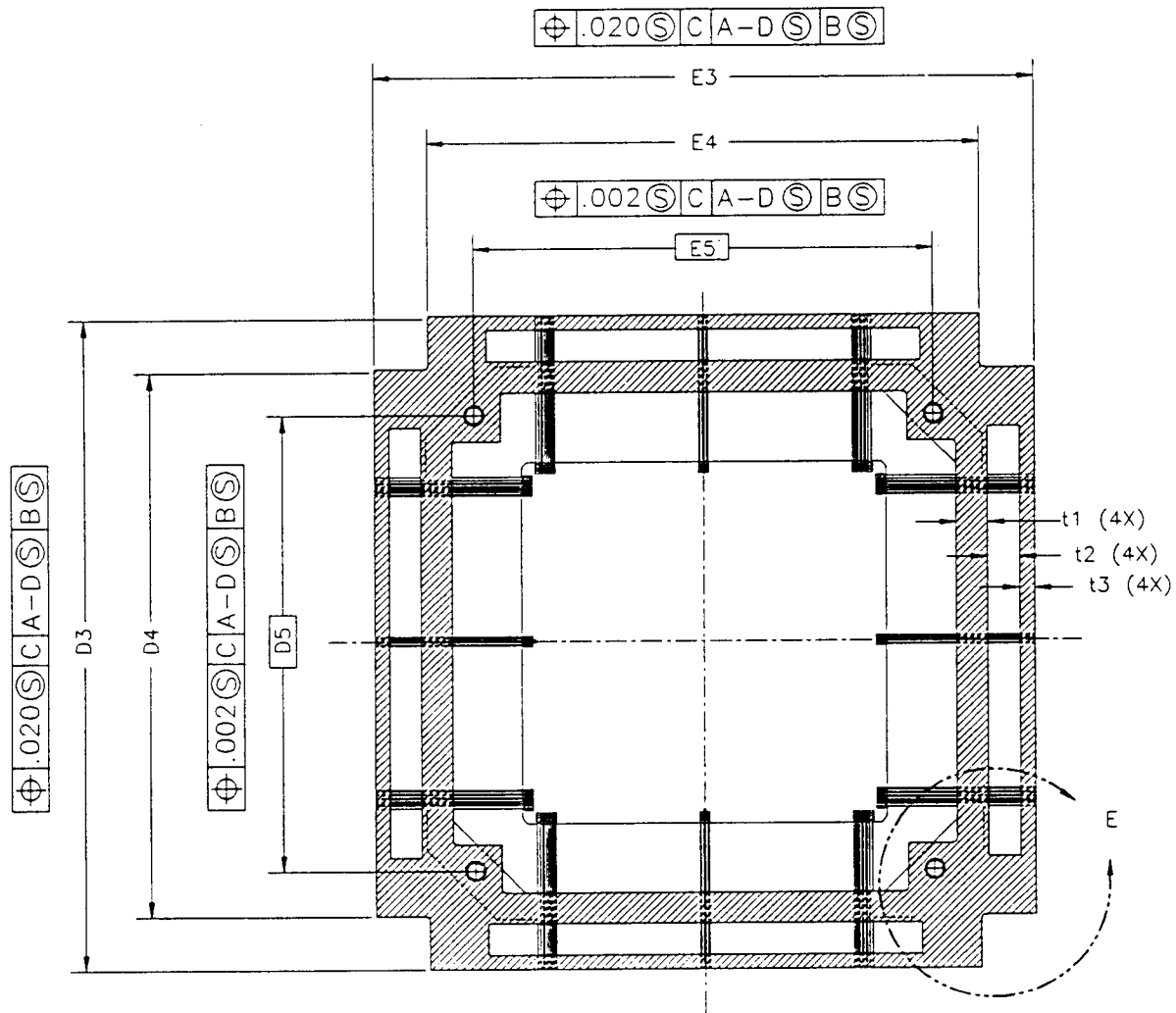


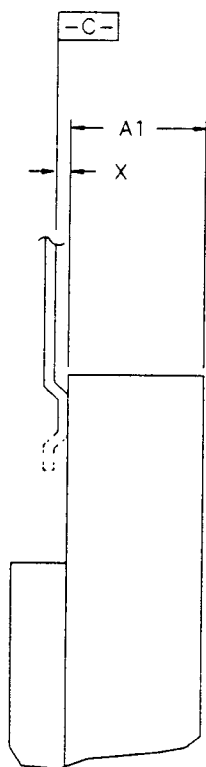
National Semiconductor has stated that U.S. Patent No. 4,796,080 may relate to a certain implementation of this package outline. The sponsor has not agreed with this statement.

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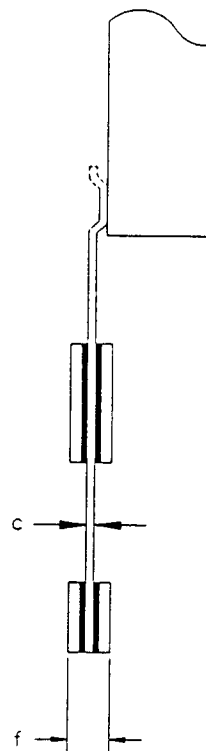
Tie Bar Detail



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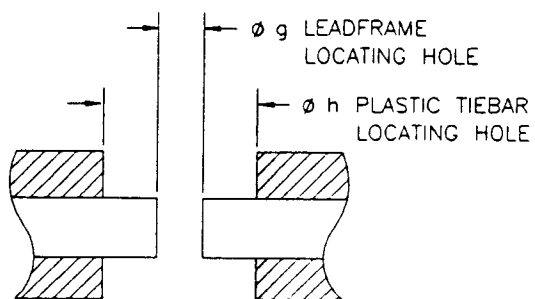


DETAIL A



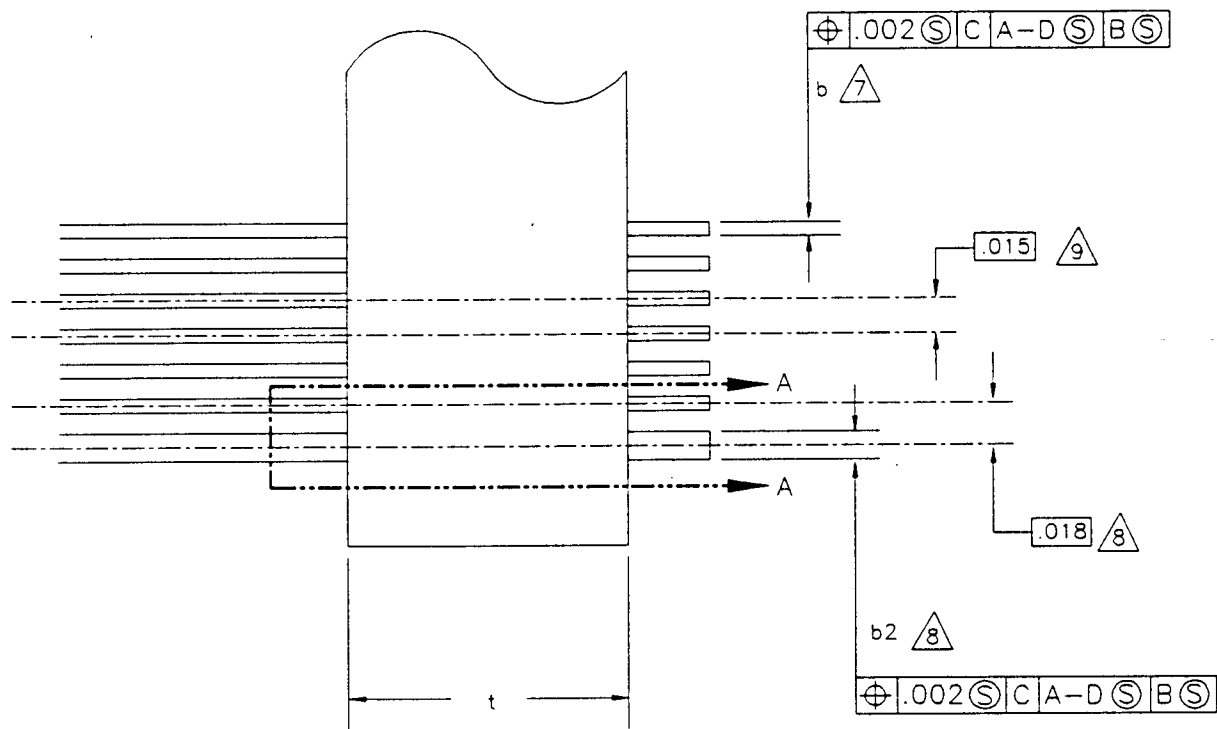
DETAIL B

6

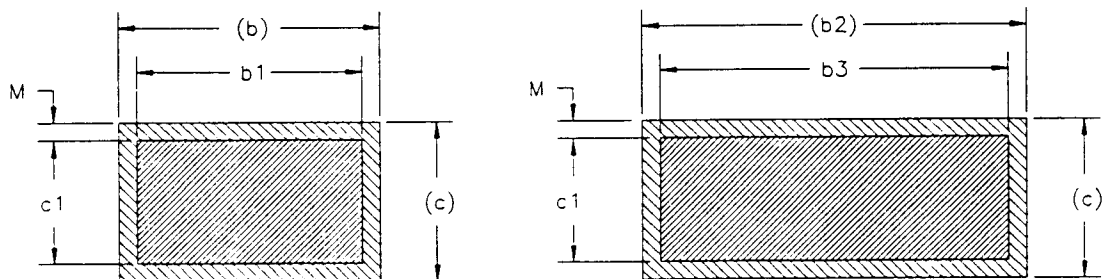


SECTION B-B

<p>JEDEC Solid State Product Outline</p>	<p>TOP BRAZED CERAMIC LEADED CHIP CARRIER (.015 INCH LEAD PITCH) WITH PLASTIC NON-CONDUCTIVE TIE BAR</p>	<p>ISSUE A</p>	<p>DATE Sept. 1992</p>	<p>MO-130</p>	<p>SHEET 3/7</p>
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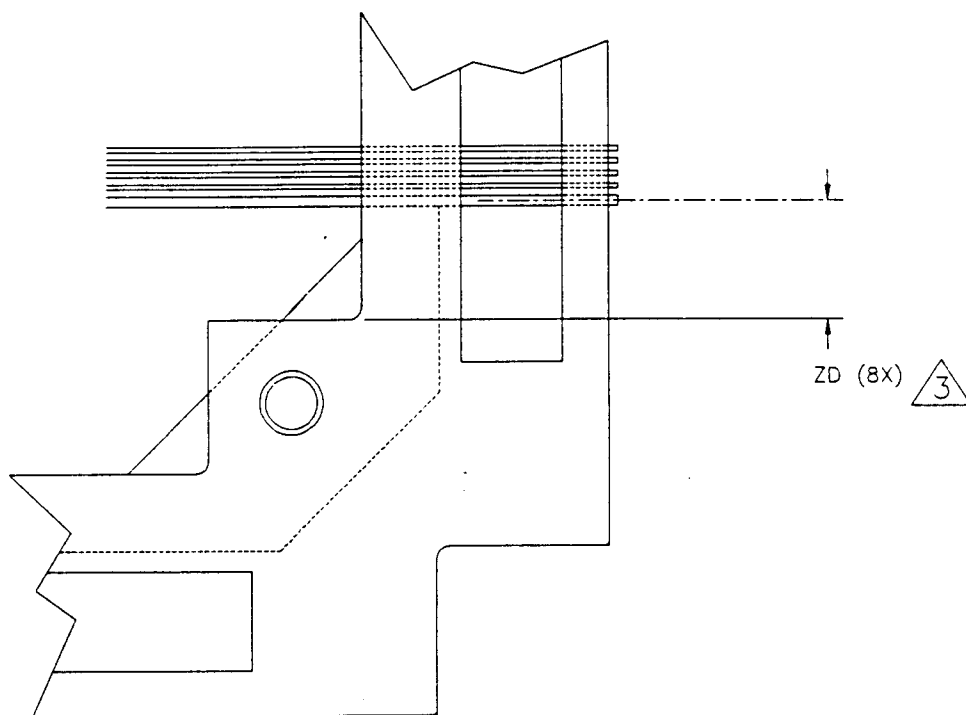


DETAIL C

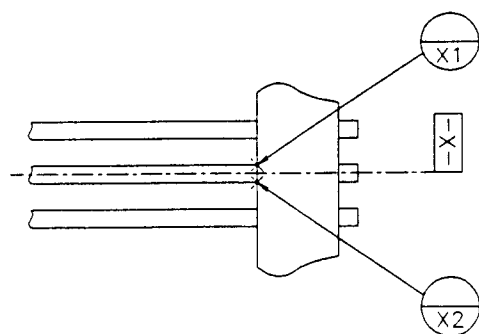


SECTION A-A 4

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DETAIL E



X = -A- , -B- OR -D-

DETAIL D

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SYMBOL	VARIATIONS			NOTE
	AA			
	MIN	NOM	MAX	
A	—	—	0.125	
A1	0.092	0.096	0.100	
b	0.005	0.006	0.007	
b1	0.0044	0.0054	0.0064	4
b2	0.011	0.012	0.013	
b3	0.0104	0.0114	0.0124	4
c	0.0025	0.003	0.004	
c1	0.0019	0.0024	0.0034	4
D	1.380	1.390	1.400	
D2	1.910	1.920	1.930	
D3	2.505	2.510	2.515	
D4	2.095	2.100	2.105	
D5	1.748	1.750	1.752	
E	1.380	1.390	1.400	
E2	1.910	1.920	1.930	
E3	2.505	2.510	2.515	
E4	2.095	2.100	2.105	
E5	1.748	1.750	1.752	
f	0.015	0.025	0.045	
g	0.063	0.064	0.065	
h	0.072	0.074	0.076	
X	0.002	0.008	0.014	
L1	0.260	0.265	0.270	
M	—	—	0.0003	4
t1	0.115	0.120	0.125	
t2	0.115	0.120	0.125	
t3	0.050	0.055	0.060	
ZD	0.184	0.204	0.224	
N		340		2
NOTE 1 . 5				
REF 10-299				
ISSUE A				

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NOTES:

1. All dimensions are in inches.
2. Dimension N: Number of leads. For drawing clarity, not all leads are shown. Actual package has a continuous array of leads.
3. Plastic tie bar will not overhang lead tips.
4. Dimension b1, b3 and c1 apply to base metal only. Dimension M applies to plating thickness.
5. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
6. These holes are to be used for locating the package during tie bar attach, electrical testing, trim, form and excise operations.
7. Occurs on N-8 places. (width for all leads except corner leads).
8. Occurs on 8 corner leads.
9. Occurs on N-12 places. (pitch for all leads except corner leads)
10. Datum A-D and -B- to be determined by datum points where leads contact the tie bar.

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